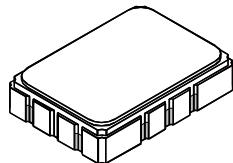


**SF2039B-3**

- **Designed for SDARS IF Receiver**
- **Low Insertion Loss**
- **5.0 X 7.0 mm Surface-Mount Case**
- **Differential or Single Ended Input and Output**
- **Complies with Directive 2002/95/EC (RoHS)**

**72.540 MHz
SAW Filter****Absolute Maximum Ratings**

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Max. DC voltage between any 2 terminals	30	VDC
Storage Temperature Range	-40 to +85	°C
Max Soldering Profile	265°C for 10 s	

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Nominal Center Frequency	f_C			72.540		MHz
Passband	Insertion Loss	IL		10.5	12.5	dB
1dB Passband	BW_1	1	3.7	4.0		MHz
15dB Bandwidth	BW_{15}			6.5	6.7	MHz
30dB Bandwidth	BW_{30}			7.5	7.7	MHz
Amplitude Ripple over $f_C \pm 1.85$ MHz				0.5	1.3	dB _{P-P}
Group Delay Variation over $f_C \pm 1.85$ MHz	GDV			60	150	ns _{P-P}
Rejection	50 to 66.48 MHz	1, 3	40	47		dB
	66.48 to 68.08 MHz		33.5	43		
	77.30 to 78.60 MHz		38	42		
	78.60 to 86.50 MHz		40	44		
	86.50 to 91.50 MHz		45	50		
	91.50 to 100.00 MHz		45	55		
Operating Temperature Range	T_A	1	-40		+85	°C
Frequency Temperature Coefficient	FTC			-18		ppm/°C
Differential Input				175 ohms		
Differential Output				1000 ohms		
Case Style		6		SMP-03-S 5 x 7 mm Nominal Footprint		
Lid Symbolization (YY=year, WW=week, S=shift) See note 4				RFM SF2039B-3 YYWWS		

Electrical Connections

Connection	Port 1 Hot	Port 1 Ground Return or Hot	Port 2 Hot	Port 2 Ground Return or Hot	Case Ground
Terminals	10	1	5	6	All Others

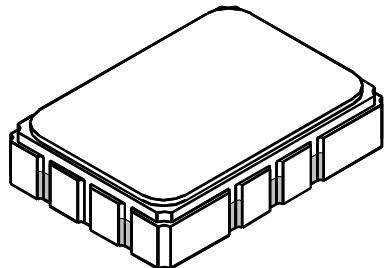
Notes:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, f_C .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Tape and Reel Standard ANSI / EIA 481.
7. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
8. US and international patents may apply.
9. RFM, stylized RFM logo, and RF Monolithics, Inc. are registered trademarks of RF Monolithics, Inc.
10. ©Copyright 1999, RF Monolithics Inc.
11. Electrostatic Sensitive Device. Observe precautions for handling.



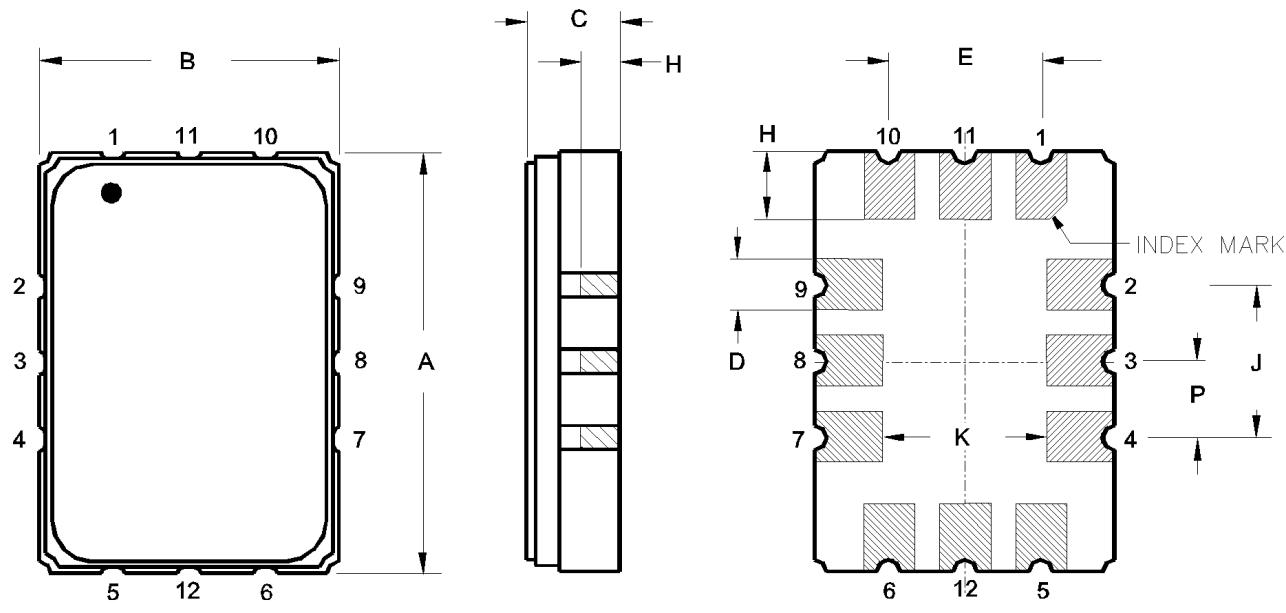
SMP-03-S Case 

12-Terminal Ceramic Surface-Mount Case
5 x 7 mm Nominal Footprint

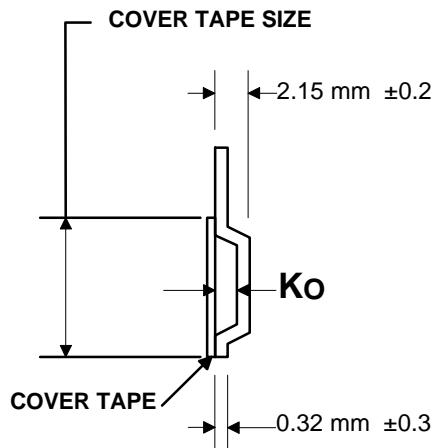
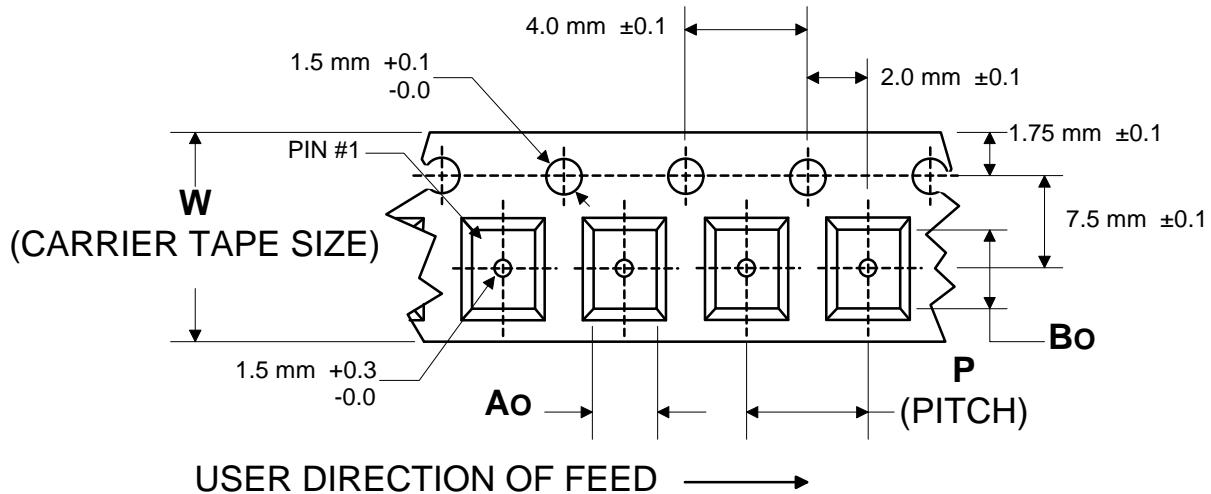


Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	6.80	7.00	7.20	0.268	0.276	0.283
B	4.80	5.00	5.20	0.189	0.197	0.205
C		1.65	2.00		0.065	0.079
D		0.80				
E	2.41	2.54	2.67	0.095	0.100	0.105
H	0.87	1.1	1.13	0.034	0.039	0.044
J		2.54				
K	2.87	3.00	3.13	0.113	0.118	0.123
P	1.14	1.27	1.40	0.045	0.050	0.055

Materials	
Solder Pad Termination	Au plating 30 - 60 micrometers (76.2-152 μ m) over 80-200 micrometers (203-508 μ m) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 micrometers Thick
Body	Al_2O_3 Ceramic
Pb Free	



COMPONENT ORIENTATION and DIMENSIONS



Carrier Tape Dimensions		
Ao	5.5 mm	±0.1
Bo	7.5 mm	±0.1
Ko	2.0 mm	±0.1
Pitch	8.0 mm	±0.1
W	16.0 mm	±0.3